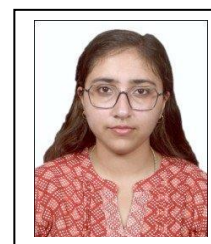


Name: Prof. Trishaani Acharjee
Designation: Assistant Professor
Branch: Computer Science Engineering



Educational Qualification(s):

Qualification(s)	University	Year of Completion
B.Tech in Electronics and Computer Science Engineering	KIIT University	2020
M.Tech in Computer Science Engineering	KIIT University	2022
Ph.D in Computer Science Engineering	KIIT University	Pursuing

Experience in years: 1.5 Years

Academic :

Details:

Sl. No.	Organization	Position Held	Duration	
			From	To
1.	KIIT University	Teaching Assistant	2020	2022

Other Information:

a) Publication details.

Patent:

- UK Registered Design: Medical Diagnostic Device for Wound Assessment**
Granted: July 2026 | Classification: Class 24 (Medical & Laboratory Equipment)
Co-inventors: T. Acharjee, R. Chatterjee, M.K. Gourisaria, T. Maitra, S. Jha, D. Singh
 - Official UKIPO-registered design for a novel diagnostic tool enabling rapid, non-invasive wound evaluation.
 - Designed in compliance with Class 24 medical instrument standards.

Journals:

1. Acharjee, Trishaani, Rajdeep Chatterjee, Biswaranjan Acharya, and Fernando Moreira. **"ERYXNet: a lightweight yet robust architecture for multi-type wound classification."** *Neural Computing and Applications* 38, no. 8 (2026): 291.
2. T. Acharjee, R. Chatterjee, M. K. Gourisaria, M. Sahni, and E. León-Castro, **"ERYXSeg: A Hybrid CNN Architecture for Robust and Resource-Aware Wound Segmentation,"** *Frontiers in Surgery*, vol. 13, Art. 1790725, 2026. doi: 10.3389/fsurg.2026.1790725 Published online: 19 June 2026.

Conferences:

1. T. Acharjee, and R. Chatterjee. **"WISENet: Towards Automated Visual Wound Analysis and Grading."** In 2026 7th International Conference on Computational Intelligence and Networks (CINE), pp. 1-6. IEEE, 2026, India.
2. Rajdeep Chatterjee, Sudip Chakrabarty, Trishaani Acharjee, Deepanjali Mishra. **"AUDRON: A Deep Learning Framework with Fused Acoustic Signatures for Drone Type Recognition."** In the 22nd edition of IEEE INDICON 2025: *Regenerative Artificial Intelligence: Advancing AI for Industrial, Societal, and Environmental Impact*.
3. T. Acharjee, and R. Chatterjee. **"Wound Image Classification with Vision Transformer and Feature Embeddings."** In 2025 6th International Conference on Recent Advances in Information Technology (RAIT), pp. 1-6. IEEE, 2025, India.
4. Acharjee, Trishaani, and Rajdeep Chatterjee. **"Wound Classification: Database Construction Through Image Processing and Region of Interest Detection."** In *2024 4th International Conference on Computer, Communication, Control & Information Technology (C3IT)*, pp. 1-7. IEEE, 2024.
5. Acharjee, Trishaani, Roshni Pradhan, Amiya Kumar Dash, Suresh Chandra Satapathy, and Milan Simic. **"A Survey on Medical Image Analysis Using Deep Learning."** In *International Conference on Frontiers of Intelligent Computing: Theory and Applications*, pp. 165-178. Singapore: Springer Nature Singapore, 2022.
6. Biswas, Debanshu, Ipsit Nayak, Shaibal Choudhury, Trishaani Acharjee, Sidhant, and Mayank Mishra. **"Crack detection on inner tunnel surface using image processing."** In *Progress in Advanced Computing and Intelligent Engineering: Proceedings of ICACIE 2019, Volume 1*, pp. 3-12. Springer Singapore, 2021.

(b) Details of Seminar/Workshop/Conference.

1. Poster presenter at the 16th Student Research Symposium, hosted by KIIT Deemed-to-be-University, Bhubaneswar, as part of the 22st ICDCIT conference series (March 2026).
2. Reviewer of "The 8th International Conference on Computational Intelligence and Networks", CINE 2026.
3. Poster presenter at the 15th Student Research Symposium, hosted by KIIT Deemed-to-be-University, Bhubaneswar, as part of the 21st ICDCIT conference series (January 2025).
4. Attended the "Winter School on Deep Learning for Vision and Language Modelling" at IIT Guwahati. 2025
5. Attended the "Summer School on AI" at IIIT Hyderabad. 2025

6. Reviewer of “The 7th International Conference on Computational Intelligence and Networks”, CINE 2024.

(c) . Professional membership of reputed bodies if any.

1. Member, IEEE Women in Engineering (WIE)